

# RF 200 & RF 300

## Low Cost Reflow Oven for Wafer Level Soldering



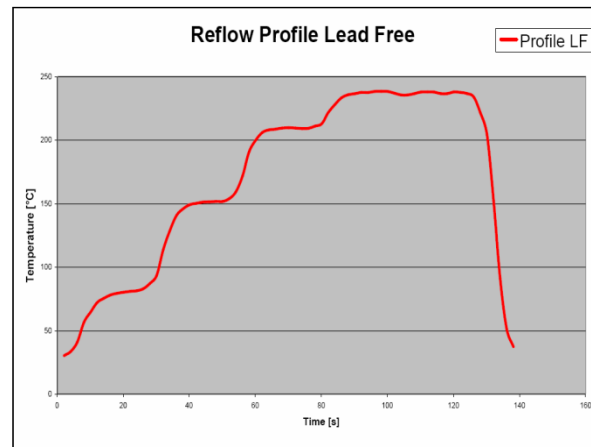
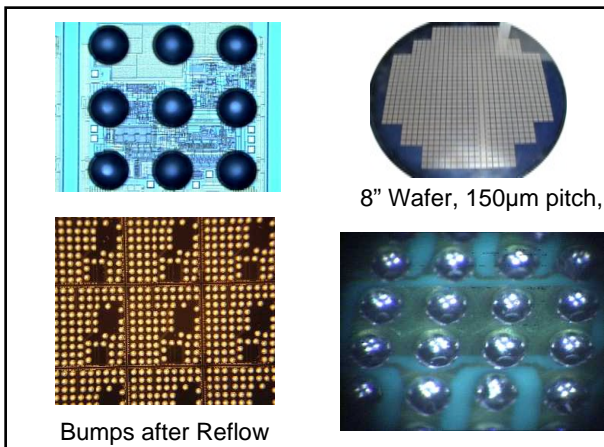
### Solder Ball Reflow on Wafer Level

#### Specifications:

- 30µm-760µm solder spheres
- Wafer sizes: 100, 150 and 200 mm for RF 200  
200 and 300 mm for RF 300
- Volume production & prototyping capability  
Wafer handler available as option
- Stainless steel body mirror shining polished
- Free adjustable time for pre delay for heating and cooling
- Temperature programmable from 0 – 350° C
- Nitrogen regulator for flow control
- Vacuum chamber @ 500 mbar (optional higher)
- Automatic handling for wafer movement to heating plate
- Reflow under inert – active gas, rest oxygen 20 ppm
- Exhaust can be connected
- Small footprint
- Inert gas consumption 50l/ min
- Wafer cooling in Inert gas



Reflow Oven RF 300



Temperature Profile

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